

PART INFORMATION		
Mfg Item Number	MK70FX512VMJ12	
Mfg Item Name	MAPBGA 256 17*17*1.7P1.0	
SUPPLIER		
Company Name	Freescale Semiconductor Inc	
Company Unique ID	14-141-7928	
Response Date	2017-12-19	
Response Document ID	00A9K00188D003A1.28	
Contact Name	Freescale Semiconductor Inc	
Contact Title	Product Technical Support	
Contact Phone	1-800-521-6274	
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Representative Title	EPP Customer Response	
Representative Phone	512-895-3406	
Representative Email	eppanlst@freescale.com	
URL for Additional Information	www.freescale.com	
DECLARATION		
EU RoHS	Yes	
Pb Free	Yes	
HalogenFree	Yes	
Plating Indicator	e1	
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number	MK70FX512VMJ12	
Mfg Item Name	MAPBGA 256 17*17*1.7P1.0	
Version	ALL	
Weight	0.892900	
UoM	g	
Unit Volume	EACH	
J-STD-020 MSL Rating	3	
Peak Processing Temperature	260 C	
Max Time at Peak Temperature	40 seconds	
Number of Processing Cycles	3	

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Solder Balls - Lead Free	0.0808						g					
Solder Balls - Lead Free		Metals	Aluminum, metal	7429-90-5		0.0000025	g	31	0.0031		2	0.0002
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.0000101	g	125	0.0125		11	0.0011
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000598	g	74	0.0074		6	0.0006
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00001511	g	187	0.0187		16	0.0016
Solder Balls - Lead Free		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.00000097	g	12	0.0012		1	0.0001
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00040352	g	4994	0.4994		451	0.0451
Solder Balls - Lead Free		Metals	Gold, metal	7440-57-5		0.00000501	g	62	0.0062		5	0.0005
Solder Balls - Lead Free		Metals	Indium, metal	7440-74-6		0.00000501	g	62	0.0062		5	0.0005
Solder Balls - Lead Free		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00000048	g	6	0.0006		0	0
Solder Balls - Lead Free		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00000501	g	62	0.0062		5	0.0005
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6		0.0000101	g	125	0.0125		11	0.0011
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1		0.0000303	g	375	0.0375		33	0.0033
Solder Balls - Lead Free		Nickel (external applications only)	Nickel	7440-02-0		0.0000025	g	31	0.0031		2	0.0002
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.0032282	g	39953	3.9953		3615	0.3615
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.07707367	g	953882	95.3882		86318	8.6318
Solder Balls - Lead Free		Metals	Zinc, metal	7440-66-6		0.00000154	g	19	0.0019		1	0.0001
Non-Conductive Epoxy/Adhesive	0.0028						g					
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00021	g	75000	7.5		235	0.0235
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00056	g	200000	20		627	0.0627
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.00021	g	75000	7.5		235	0.0235
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00056	g	200000	20		627	0.0627
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.00126	g	450000	45		1411	0.1411
Bonding Wire, Copper	0.0018						g					
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.001746	g	970000	97		1955	0.1955
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000054	g	30000	3		60	0.006
Die Encapsulant, Halogen-free	0.342						g					
Die Encapsulant, Halogen-free		Metals	Other aluminum compounds	-		0.01026	g	30000	3		11490	1.149
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00342	g	10000	1		3830	0.383
Die Encapsulant, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.01026	g	30000	3		11490	1.149
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.01026	g	30000	3		11490	1.149
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.2907	g	850000	85		325589	32.5589
Die Encapsulant, Halogen-free		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.0171	g	50000	5		19151	1.9151
Organic Substrate, Halogen-free	0.4356						g					
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.01711777	g	39297	3.9297		19170	1.917
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.2181376	g	500775	50.0775		244302	24.4302
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 862	28064-14-4		0.02346969	g	53879	5.3879		26284	2.6284
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.0012615	g	2896	0.2896		1412	0.1412
Organic Substrate, Halogen-free		Nickel (external applications only)	Nickel	7440-02-0		0.00985414	g	22622	2.2622		11036	1.1036
Organic Substrate, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.01281622	g	29422	2.9422		14353	1.4353
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.0784986	g	180208	18.0208		87914	8.7914
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.00672828	g	15446	1.5446		7535	0.7535
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.00274864	g	6310	0.631		3078	0.3078
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-51-2		0.03844736	g	88263	8.8263		43058	4.3058
Organic Substrate, Halogen-free		Plastics/polymers	Epoxy Resin	115254-47-2		0.0265202	g	60882	6.0882		29701	2.9701
Silicon Semiconductor Die	0.0299						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000588	g	20000	2		669	0.0669
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.029302	g	980000	98		32816	3.2816

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MK70FX512VMJ12_IPC1752_v11.xml

http://www.freescale.com/mcds/MK70FX512VMJ12_IPC1752A.xml